

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5706	((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89,85,86)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/02 22:55
L2	0	L1 and ((polish\$3 with (first metal layer)) same (detect\$3 with (end point))) and (clean\$3 with (surface or platen)) and (polish\$3 with (second metal layer)) and ((measur\$3 with (second metal layer)) same optic\$3) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same dry same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:34
L3	0	((polish\$3 with (first metal layer)) same (detect\$3 with (end point))) and (clean\$3 with (surface or platen)) and (polish\$3 with (second metal layer)) and ((measur\$3 with (second metal layer)) same optic\$3) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same dry same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:06
L5	0	L1 and ((polish\$3 same (first metal layer)) same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same dect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:47
L6	0	((polish\$3 same (first metal layer)) same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same dect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4) same (film thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:53

L7	0	((polish\$3 same (first metal layer)) same (detect\$3 same (end point))) and (polish\$3 same (second metal layer) same detect\$3 same (end point)) and ((clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and ((detect\$4 or measur\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 21:54
L8	3	(polish\$3 and (first metal layer) and (detect\$3 with (end point)) and (second metal layer) and (clean\$3 with (substrate or wafer or workpiece)) same dry\$3) and (detect\$4 or measur\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:08
L9	39	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89,85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L10	295	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89,85,86)).CCLS.) and (polish\$3 with load)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L11	15	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89,85,86)).CCLS.) and polish\$3 same (rins\$4 with water) and (metal adj layer)) and (@rlad<="20001001" or @ad<="20001001") and load	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L12	4	(((((156/345.12,345.13,345.15) or (438/692,14) or (216/88,38,84,89,85,86)).CCLS.) and ((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L13	26	((polish\$3 with load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L14	2	((pressing adj load) with (tungsten or copper or (conductive adj layer)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L15	2	((pressing adj load) same (metal adj layer))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39

L16	281	(polish\$3 same load same ((metal adj layer) or tungsten or copper))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L17	68	((((polish\$3 same load same ((metal adj layer) or tungsten or copper))) and titanium) and (@rlad<="20001001" or @ad<="20001001"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:39
L18	92	(load same CMP same change) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 22:57
L19	428	(L9 or L10 or L11 or L12 or L13 or L14 or L15 or L16 or L17 or L18) and @pd>="2000510" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:40
L20	4	(L9 or L10 or L11 or L12 or L13 or L14 or L15 or L16 or L17 or L18) and @pd>="20050510" and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:40
L21	361	1 and (measure same ((film or layer) with thickness))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2005/10/02 22:56
L22	154	(21) and (@rlad<="20001001" or @ad<="20001001")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 23:34
L23	86	22 and cmp	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/02 23:35